Peter Schneider

List of Publications by Year
in descending order

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26	146	2258059 3	1872680 6
papers	citations	h-index	g-index

28	28	28	83
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	A modular approach for simulation-based optimization of MEMS. Microelectronics Journal, 2002, 33, 29-38.	2.0	22
2	Developing digital test sequences for through-silicon vias within 3D structures. , 2010, , .		18
3	Modular approach for simulation-based optimization of MEMS. , 2000, 4228, 71.		12
4	Design of multi-dimensional magnetic position sensor systems based on HallinOne^{Â®} technology. , 2010, , .		12
5	<title>Model library and tool support for MEMS simulation</title>. , 2001, , .		11
6	System Level Modeling of Microsystems Using Order Reduction Methods. Analog Integrated Circuits and Signal Processing, 2003, 37, 7-16.	1.4	11
7	Design support for Wireless Sensor Networks based on the IEEE 802.15.4 standard. , 2008, , .		8
8	Challenges of simulating robust wireless sensor network applications in building automation environments. , 2010, , .		8
9	<title>System-level modeling of microsystems using order reduction methods</title>. , 2002, , .		7
10	Towards a methodology for analysis of interconnect structures for 3D-integration of micro systems. Analog Integrated Circuits and Signal Processing, 2008, 57, 205-211.	1.4	7
11	System level simulation â€" A core method for efficient design of MEMS and mechatronic systems. , 2012, , .		6
12	FunctionalDMU: Co-Simulation of Mechatronic Systems in a Virtual Environment. , 2011, , .		4
13	<title>MOSCITO: a program system for MEMS optimization</title>. , 2002, , .		3
14	Design Support for 3D System Integration by Multi Physics Simulation. , 2008, , .		3
15	Integration of multi physics modeling of 3D stacks into modern 3D data structures. , 2010, , .		2
16	Simulation of electro-thermal interaction. , 2010, , .		2
17	Sensitivity analysis and adaptive multi-point multi-moment model order reduction in MEMS design. Analog Integrated Circuits and Signal Processing, 2012, 71, 49-58.	1.4	2
18	System Level Modeling of the Relevant Physical Effects of Inertial Sensors Using Order Reduction Methods. Analog Integrated Circuits and Signal Processing, 2005, 44, 129-135.	1.4	1

#	ARTICLE	IF	CITATIONS
19	Modular modeling approach to consider RF and thermal behavior of complex systems built up using interconnect structures in 3D integration. , 2010, , .		1
20	Electro-thermal co-design of chip-package-board systems. , 2013, , .		1
21	Design rule check and layout versus schematic for 3D integration and advanced packaging. , 2014, , .		1
22	Current and future 3D activities at Fraunhofer. , 2015, , .		1
23	Simulation platform for application development on a vision-system-on-chip with integrated signal processing. Journal of Electronic Imaging, 2016, 25, 041004.	0.9	1
24	<title>System-level simulation of acoustic devices</title>. , 2002, 4755, 343.		0
25	Model based sensor system for temperature measurement in R744 air conditioning systems. , 2008, , .		0
26	Fraunhofer's Initial and Ongoing Contributions in 3D IC Integration. , 2019, , .		0